

Special Issue

Plasma Physics: Theory, Methods and Applications

Message from the Guest Editor

This Special Issue related to plasma physics is focused on the theory, method, and application of plasma. Therefore, we welcome the submission of any type of works that report on the generation of laboratory plasma, the investigation of its property by means of numerical simulation and experimental diagnostics, and the application of plasma, including both low-temperature and high-temperature plasmas. Moreover, this Special Issue is also suited for the submission of works that attempt to build relations between laboratory plasma and astrophysics plasma. **Keywords**

- low-temperature plasma
- thermal nuclear fusion plasma
- film deposition and etching process
- numerical simulation and experimental diagnostic
- astrophysics plasma
- thermal and chemical equilibrium

Guest Editor

Dr. Shuxia Zhao

School of Physics, Dalian University of Technology, Dalian 116024, China

Deadline for manuscript submissions

20 September 2025



Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.3



mdpi.com/si/199927

Applied Sciences
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)





Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.3



[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPIus / SciFinder, and other databases.

Journal Rank:

JCR - Q1 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)